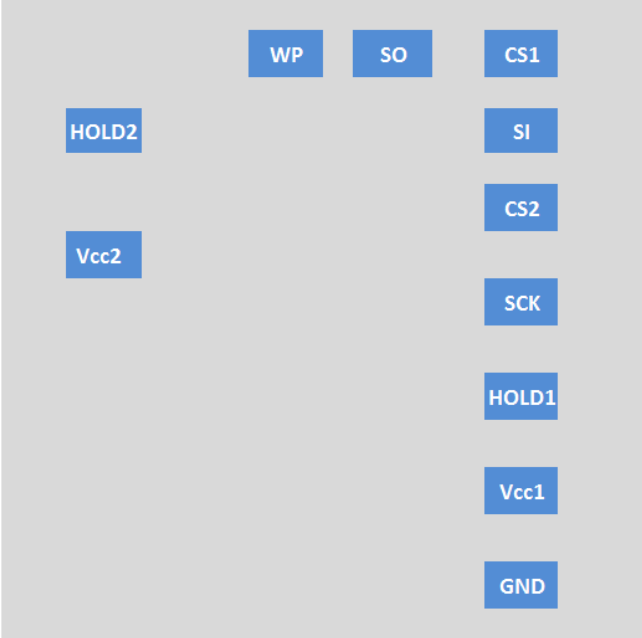
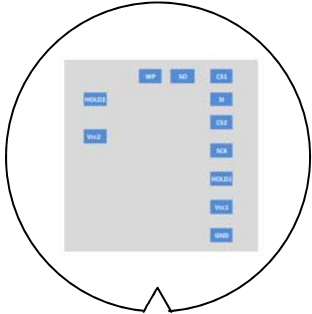


WAFER PRODUCT PRELIMINARY DATASHEET (ADDENDUM)

Product	AT25XE041B-DRDA and AT25XE041B-DRDAHT
Description	4Mbit, Fusion, 1.65V – 3.6V VCC
Die Pad Layer	  <p data-bbox="1154 1623 1487 1688">Wafer to die orientation Die logo not visible on RDL; use wafer notch for die orientation</p>

Pad Coordinates (relative to center)	X (μm)	Y (μm)
	Die Size	1540
Scribe Width	80	80
Pad Opening (RDL)	65	65
CS1	440.00	600.00
CS2	400.00	300.00
GND	500.00	-650.00
HOLD1	500.00	-50.00
HOLD2	-500.00	450.00
SCK	400.00	150.00
SI	400.00	450.00
SO	250.00	600.00
VCC1	500.00	-350.00
VCC2	-500.00	300.00
WP	100.00	600.00

Technical Details	
Adesto Product Family	Fusion
Density	4 Mbit
Operating Vcc	1.65V - 3.6V
ESD	>2kV JESD22-A114
Delivery Option	Wafer- unsawn
Wafer Size (mm)	200
Process Geometry (nm)	110
Die ID	637S5
Wafer Map	Electronic- text file
Manufacturing Facility	UMC
Wafer Thickness (μm) Maximum ²	745
Back Grind Options ²	None / Contact Adesto
Back Plane Connection ²	Floating / Not Required
Backside preparation / metallization ²	None
Passivation Material ²	HDP oxide + SiON
Passivation Thickness (Å) ²	21000
Bond Pad Material ²	Ti/TiN/AlCu
Bond Pad Thickness (Å) ²	6000
Good Die per Wafer	Contact Adesto (AT25XE041B-DRDA) ¹
Good Die per Wafer	Contact Adesto (AT25XE041B-DRDAHT) ¹
Active Circuits Underneath the Bond Pad	No
RDL Passivation 1 Material	PBO Polybenzoxazole
RDL Passivation 1 Thickness (Å)	75000
RDL Passivation 2 Material	PBO Polybenzoxazole
RDL Passivation 2 Thickness (Å)	75000
RDL Metallization Material	Cu
RDL Metallization Thickness (Å)	40000
RDL Bond Pad Material	TiW/Cu/Ni/Au
RDL Bond Pad Thickness (Å)	115000
RDL Bond wire qualified	AU <input checked="" type="checkbox"/> CU <input type="checkbox"/> AG <input type="checkbox"/>

¹ Average value; subject to change without notice.

² Original die material construction and dimensions.

Part Number Ordering Code ³	Operating Temperature Range	Functional Specification
AT25XE041B-DRDA	-40°C to 85°C	http://www.adestotech.com/wp-content/uploads/DS-AT25XE041B-062.pdf
AT25XE041B-DRDAHT	-40°C to 125°C	http://www.adestotech.com/wp-content/uploads/DS-AT25XE041B-HRADD.pdf

³ Handle product in accordance with UV and ESD precautions.

Revision Level – Release Date	History
AA – November 2015	Initial release.
BB – August 2016	Corrected unit of measure (removed mm). Updated wafer thickness. Updated pad signals.

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